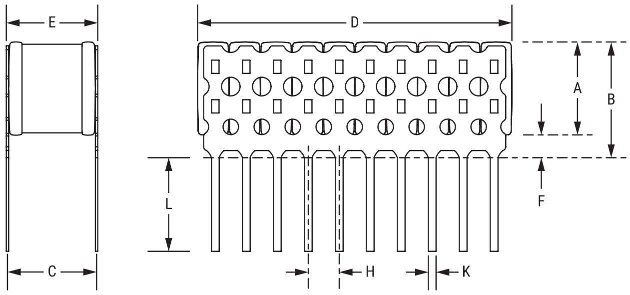
YAGEO GROUP
KEMET

# L1GN702125KA10

KPS-MCL Indust C0G HT200C, Ceramic, 1.2 uF, 10%, 200 VDC, C0G



Click here for the 3D model.

## General Information

| | |
|---|---|
| Series | KPS-MCL Indust C0G HT200C |
| Style | Leaded Stacked Chip |
| Description | Low Loss, Low ESR, Stacked Ceramic Chips |
| Features | 200C, Low ESR, High Thermal Stability, Bulk Capacitance |
| RoHS | Yes |
| SCIP Number | 297427bb-2a48-4853-b594-641304a2cc24 |
| Termination | Silver |
| Lead | Straight Leads |
| Notes | Number of chips in this stack: 10. |

## Dimensions

| | |
|---|---|
| D | 26.9mm MAX |
| L | 6.35mm MIN |
| H | 2.54mm +/-0.127mm |
| F | 1.397mm +/-0.25mm |
| A | 6.6mm MAX |
| B | 8.64mm MAX |
| C | 6.35mm +/-0.635mm |
| E | 7.62mm MAX |
| K | 0.5mm +/-0.05mm |

## Specifications

| | |
|---|---|
| Capacitance | 1.2 uF |
| Tolerance | 10% |
| Voltage DC | 200 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+200°C |
| Temp. Coefficient | C0G |
| Dissipation Factor | 0.1% 1 kHz 25C |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 830 MOhms |

## Packaging Specifications

| | |
|---|---|
| Packaging | Waffle, Box |
| Packaging Quantity | 25 |